- Three-State Versions of '151, 'LS151, 'S151
- Three-State Outputs Interface Directly with System Bus
- Perform Parallel-to-Serial Conversion
- Permit Multiplexing from N-lines to One Line
- Complementary Outputs Provide True and Inverted Data
- Fully Compatible with Most TTL Circuits

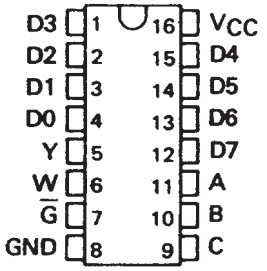
TYPE	MAX NO. OF COMMON OUTPUTS	TYPICAL AVG PROP DELAY TIME (D TO Y)	TYPICAL POWER DISSIPATION
SN54251	49	17 ns	250 mW
SN74251	129	17 ns	250 mW
SN54LS251	49	17 ns	35 mW
SN74LS251	129	17 ns	35 mW
SN54S251	39	8 ns	275 mW
SN74S251	129	8 ns	275 mW

description

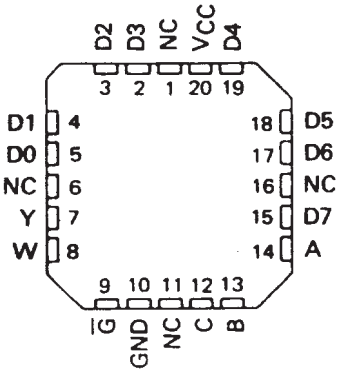
These monolithic data selectors/multiplexers contain full on-chip binary decoding to select one-of-eight data sources and feature a strobe-controlled three-state output. The strobe must be at a low logic level to enable these devices. The three-state outputs permit a number of outputs to be connected to a common bus. When the strobe input is high, both outputs are in a high-impedance state in which both the upper and lower transistors of each totem-pole output are off, and the output neither drives nor loads the bus significantly. When the strobe is low, the outputs are activated and operate as standard TTL totem-pole outputs.

To minimize the possibility that two outputs will attempt to take a common bus to opposite logic levels, the output control circuitry is designed so that the average output disable time is shorter than the average output enable time. The SN54251 and SN74251 have output clamp diodes to attenuate reflections on the bus line.

SN54251, SN54LS251, SN54S251 . . . J OR W PACKAGE
SN74251 . . . N PACKAGE
SN74LS251, SN74S251 . . . D OR N PACKAGE
(TOP VIEW)



SN54LS251, SN54S251 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

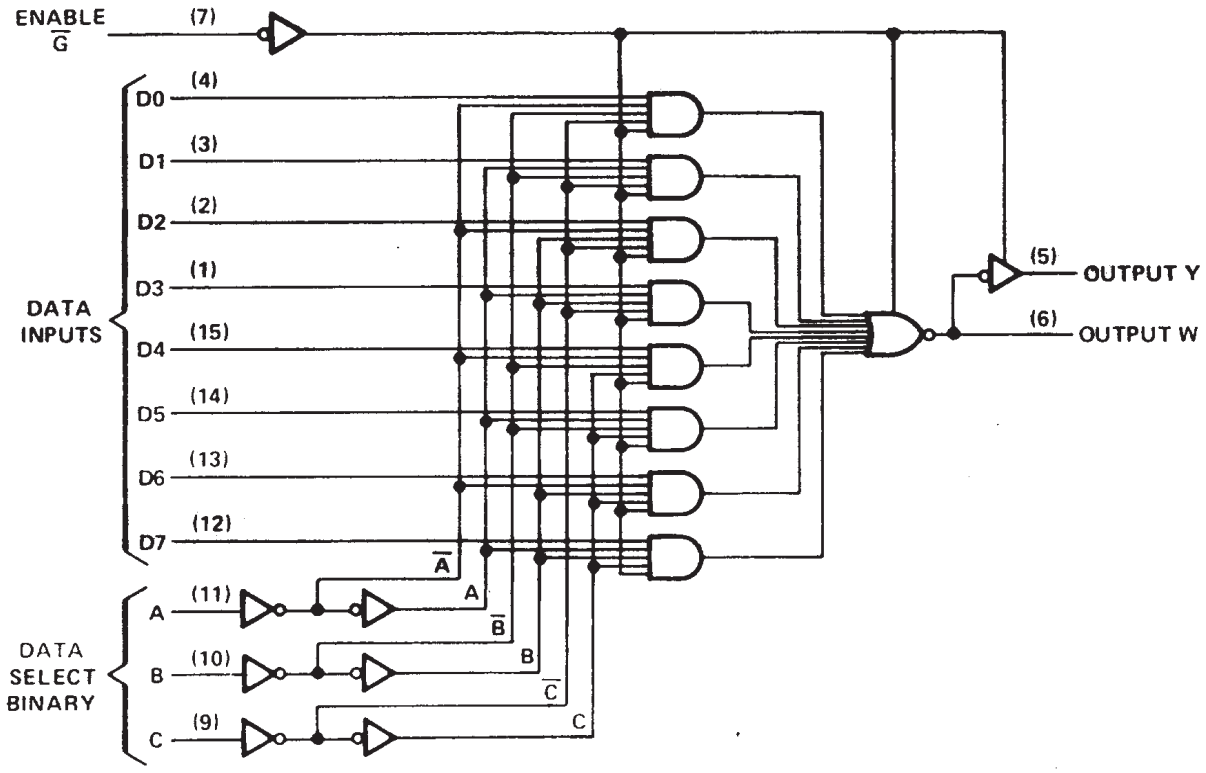
INPUTS				OUTPUTS	
SELECT			ENABLE		
C	B	A	$\overline{G}$	Y	W
X	X	X	H	Z	Z
L	L	L	L	D0	$\overline{D0}$
L	L	H	L	D1	$\overline{D1}$
L	H	L	L	D2	$\overline{D2}$
L	H	H	L	D3	$\overline{D3}$
H	L	L	L	D4	$\overline{D4}$
H	L	H	L	D5	$\overline{D5}$
H	H	L	L	D6	$\overline{D6}$
H	H	H	L	D7	$\overline{D7}$

H = high logic level, L = low logic level
X = irrelevant, Z = high impedance (off)
D0, D1 . . . D7 = the level of the respective D input

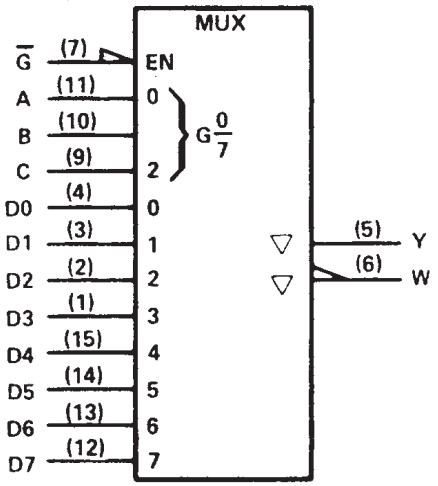
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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logic diagram (positive logic)



logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Off-state output voltage . . . . . 5.5 V
Operating free-air temperature range: SN54251 . . . . . −55°C to 125°C
SN74251 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54251			SN74251			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			−2			−5.2	mA
Low-level output current, I_{OL}			16			16	mA
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V_{IH}	High-level input voltage			2			V
V_{IL}	Low-level input voltage					0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN, I_I = −12 mA				−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = MAX		2.4	3.2		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 16 mA			0.2	0.4	V
I_{OZ}	Off-state (high-impedance-state) output current	V_{CC} = MAX, V_{IH} = 2 V	V_O = 2.4 V			40	μA
			V_O = 0.4 V			−40	
V_O	Output clamp voltage	V_{CC} = MAX, V_{IH} = 4.5 V	I_O = −12 mA			−1.5	V
			I_O = 12 mA			V_{CC}+1.5	
I_I	Input current at maximum input voltage	V_{CC} = MAX, V_I = 5.5 V				1	mA
I_{IH}	High-level input current	V_{CC} = MAX, V_I = 2.4 V				40	μA
I_{IL}	Low-level input current	V_{CC} = MAX, V_I = 0.4 V				−1.6	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX		−18		−55	mA
I_{CC}	Supply current	V_{CC} = MAX, All outputs open	All inputs at 4.5 V,		38	62	mA

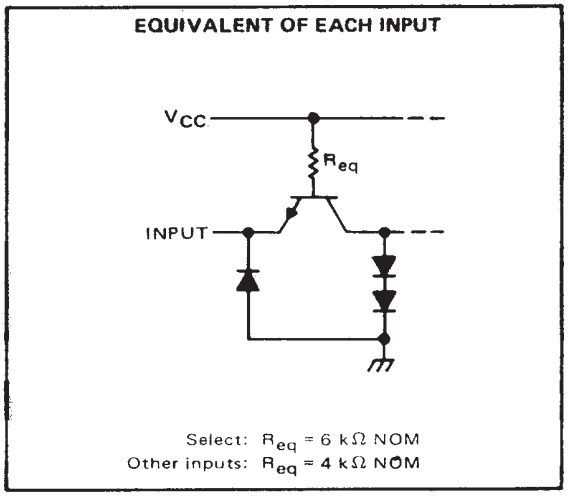
†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time.

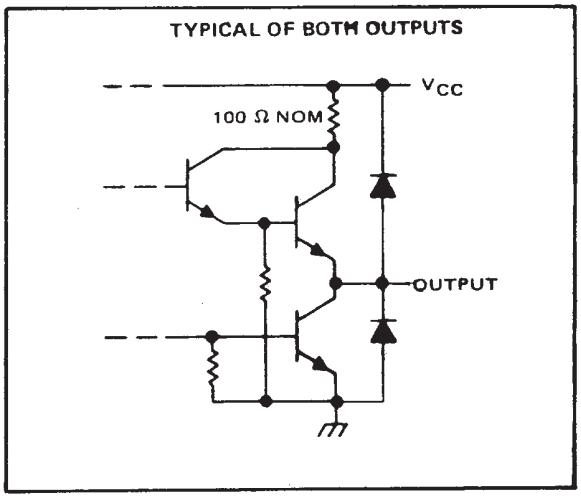
switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A, B, or C (4 levels)	Y	C_L = 50 pF, R_L = 400 Ω, See Note 2		29	45	ns
t_{PHL}					28	45	
t_{PLH}	A, B, or C (3 levels)	W			20	33	ns
t_{PHL}					21	33	
t_{PLH}	Any D	Y			17	28	ns
t_{PHL}					18	28	
t_{PLH}	Any D	W			10	15	ns
t_{PHL}					9	15	
t_{PZH}	$\overline{G}$	Y			17	27	ns
t_{PZL}					26	40	
t_{PZH}	$\overline{G}$	W			17	27	ns
t_{PZL}					24	40	
t_{PHZ}	$\overline{G}$	Y	C_L = 5 pF, R_L = 400 Ω, See Note 2		5	8	ns
t_{PLZ}					15	23	
t_{PHZ}	$\overline{G}$	W			5	8	ns
t_{PLZ}					15	23	

†t_{PLH} = Propagation delay time, low-to-high-level output
t_{PHL} = Propagation delay time, high-to-low-level output
t_{PZH} = Output enable time to high level
t_{PZL} = Output enable time to low level
t_{PHZ} = Output disable time from high level
t_{PLZ} = Output disable time from low level
NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

schematics of inputs and outputs





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Off-state output voltage . . . . . 5.5 V
Operating free-air temperature range: SN54LS251 . . . . . 55°C to 125°C
SN74LS251 . . . . . 0°C to 70°C
Storage temperature range . . . . . –65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS251			SN74LS251			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			– 1			– 2.6	mA
I_{OL}	Low-level output current			4			8	mA
T_A	Operating free-air temperature	– 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS251			SN74LS251			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}		V_{CC} = MIN, I_I = – 18 mA				– 1.5			– 1.5	V
V_{OH}		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX, I_{OH} = MAX		2.4	3.4		2.4	3.1		V
V_{OL}		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
			I_{OL} = 8 mA					0.35	0.5	
I_{OZ}		V_{CC} = MAX, V_{IH} = 2 V	V_O = 2.7 V			20			20	μA
			V_O = 0.4 V			–20			– 20	
I_I		V_{CC} = MAX, V_I = 7 V				0.1			0.1	mA
I_{IH}		V_{CC} = MAX, V_I = 2.7 V				20			20	μA
I_{IL}	Enable $\overline{G}$	V_{CC} = MAX, V_I = 0.4				– 0.2			– 0.2	mA
	All other					– 0.4			– 0.4	
I_{OS}§		V_{CC} = MAX		– 30		– 130	– 30		– 130	mA
I_{CC}		V_{CC} = MAX, See Note 3	Condition A		6.1	10		6.1	10	mA
			Condition B		7.1	12		7.1	12	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.
NOTE 3: I_{CC} is measured with the outputs open and all data and select inputs at 4.5 V under the following conditions:
A. Enable grounded.
B. Strobe at 4.5 V.

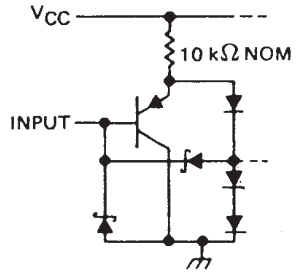
switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A, B, or C (4 levels)	Y	C_L = 15 pF, R_L = 2 kΩ, See Note 2		29	45	ns
t_{PHL}					28	45	
t_{PLH}	A, B, or C (3 levels)	W			20	33	ns
t_{PHL}					21	33	
t_{PLH}	Any D	Y			17	28	ns
t_{PHL}					18	28	
t_{PLH}	Any D	W			10	15	ns
t_{PHL}					9	15	
t_{PZH}	$\overline{G}$	Y			30	45	ns
t_{PZL}					26	40	
t_{PZH}	$\overline{G}$	W			17	27	ns
t_{PZL}					24	40	
t_{PHZ}	$\overline{G}$	Y	C_L = 5 pF, R_L = 2 kΩ, See Note 2		30	45	ns
t_{PLZ}					15	25	
t_{PHZ}	$\overline{G}$	W			37	55	ns
t_{PLZ}					15	25	

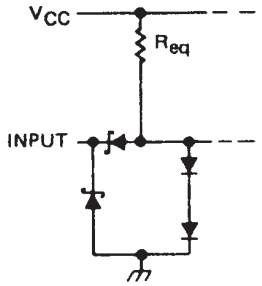
†t_{PLH} = Propagation delay time, low-to-high-level output
t_{PHL} = Propagation delay time, high-to-low-level output
t_{PZH} = Output enable time to high level
t_{PZL} = Output enable time to low level
t_{PHZ} = Output disable time from high level
t_{PLZ} = Output disable time from low level
NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

schematics of inputs and outputs

EQUIVALENT OF $\overline{G}$ INPUT

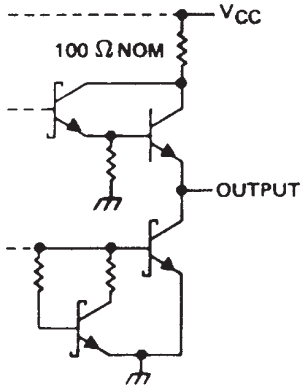


EQUIVALENT OF ALL OTHER INPUTS



A, B, C: R_{eq} = 20 kΩ NOM
D0 thru D7: R_{eq} = 17 kΩ NOM

TYPICAL OF BOTH OUTPUTS



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Off-state output voltage . . . . . 5.5 V
Operating free-air temperature range: SN54S251 . . . . . −55°C to 125°C
SN74S251 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54S251			SN74S251			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			−2			−6.5	mA
Low-level output current, I_{OL}			20			20	mA
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†			MIN	TYP‡	MAX	UNIT
V_{IH}	High-level input voltage				2			V
V_{IL}	Low-level input voltage						0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = −18 mA				−1.2	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IH} = 2 V,		SN54S'	2.4	3.4		V
		V_{IL} = 0.8 V,	I_{OH} = MAX	SN74S'	2.4	3.2		
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IH} = 2 V,					0.5	V
		V_{IL} = 0.8 V,	I_{OL} = 20 mA					
I_{OZ}	Off-state (high-impedance-state) output current	V_{CC} = MAX,	V_O = 2.4 V				50	μA
		V_{IH} = 2 V	V_O = 0.5 V				−50	
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 5.5 V				1	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V				50	μA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.5 V				−2	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX			−40		−100	mA
I_{CC}	Supply current	V_{CC} = MAX, All inputs at 4.5 V, All outputs open				55	85	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

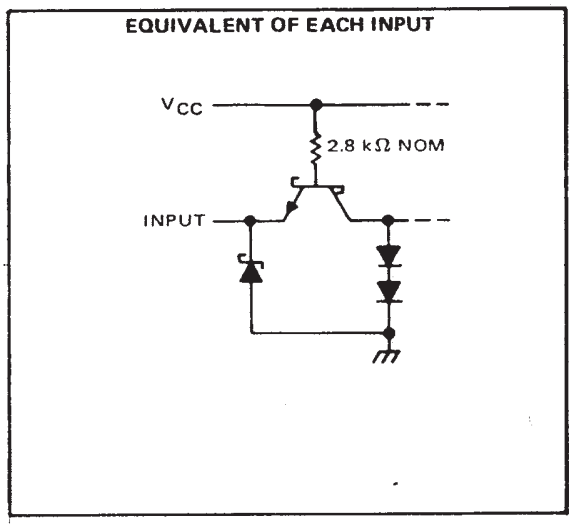
switching characteristics, V_{CC} = 5 V, T_A = 25°C

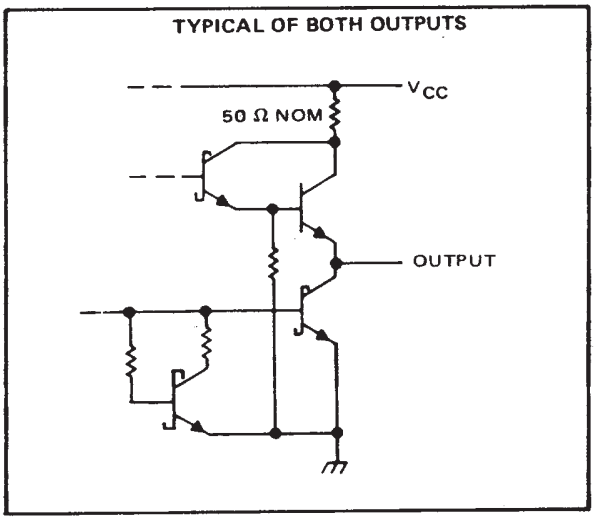
PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A, B, or C (4 levels)	Y	C_L = 15 pF, R_L = 280 Ω, See Note 2		12	18	ns
t_{PHL}					13	19.5	
t_{PLH}	A, B, or C (3 levels)	W			10	15	ns
t_{PHL}					9	13.5	
t_{PLH}	Any D	Y			8	12	ns
t_{PHL}					8	12	
t_{PLH}	Any D	W			4.5	7	ns
t_{PHL}					4.5	7	
t_{PZH}	$\overline{G}$	Y	C_L = 50 pF, R_L = 280 Ω, See Note 2		13	19.5	ns
t_{PZL}					14	21	
t_{PZH}	$\overline{G}$	W			13	19.5	ns
t_{PZL}					14	21	
t_{PHZ}	$\overline{G}$	Y	C_L = 5 pF, R_L = 280 Ω, See Note 2		5.5	8.5	ns
t_{PLZ}					9	14	
t_{PHZ}	$\overline{G}$	W			5.5	8.5	ns
t_{PLZ}					9	14	

† t_{PLH} = Propagation delay time, low-to-high-level output
t_{PHL} = Propagation delay time, high-to-low-level output
t_{PZH} = Output enable time to high level
t_{PZL} = Output enable time to low level
t_{PHZ} = Output disable time from high level
t_{PLZ} = Output disable time from low level

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

schematics of inputs and outputs





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
7601601EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601601EA SNJ54LS251J	Samples
7601601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601601FA SNJ54LS251W	Samples
7601601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601601FA SNJ54LS251W	Samples
8002201EA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
8002201EA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
8002201FA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
8002201FA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/07905BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/07905BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/30905BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30905BEA	Samples
JM38510/30905BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30905BEA	Samples
M38510/30905BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30905BEA	Samples
M38510/30905BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30905BEA	Samples
SN54251J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN54251J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN54LS251J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS251J	Samples
SN54LS251J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS251J	Samples
SN54S251J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN54S251J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN74251N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74251N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74251N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74251N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS251D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS251	Samples
SN74LS251D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS251	Samples
SN74LS251DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS251	Samples
SN74LS251DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS251	Samples
SN74LS251N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS251N	Samples
SN74LS251N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS251N	Samples
SN74LS251N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS251N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS251NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS251N	Samples
SN74LS251NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS251N	Samples
SN74LS251NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS251	Samples
SN74LS251NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS251	Samples
SN74S251D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74S251D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74S251N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74S251N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74S251N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74S251N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SNJ54251J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54251J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS251FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 251FK	Samples
SNJ54LS251FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 251FK	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS251J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601601EA SNJ54LS251J	Samples
SNJ54LS251J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601601EA SNJ54LS251J	Samples
SNJ54LS251W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601601FA SNJ54LS251W	Samples
SNJ54LS251W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601601FA SNJ54LS251W	Samples
SNJ54S251FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54S251FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54S251J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54S251J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54S251W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54S251W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54251, SN54LS251, SN54S251, SN74251, SN74LS251, SN74S251 :

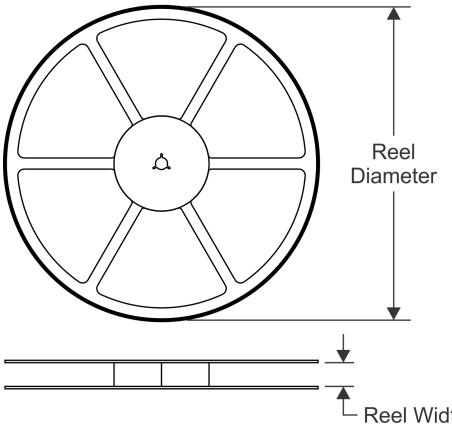
- Catalog: SN74251, SN74LS251, SN74S251
- Military: SN54251, SN54LS251, SN54S251

NOTE: Qualified Version Definitions:

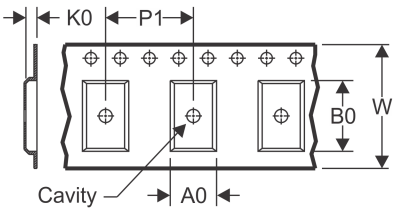
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

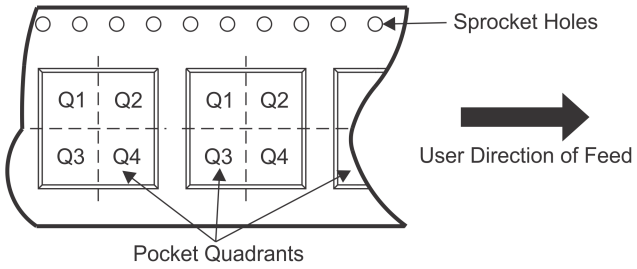


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

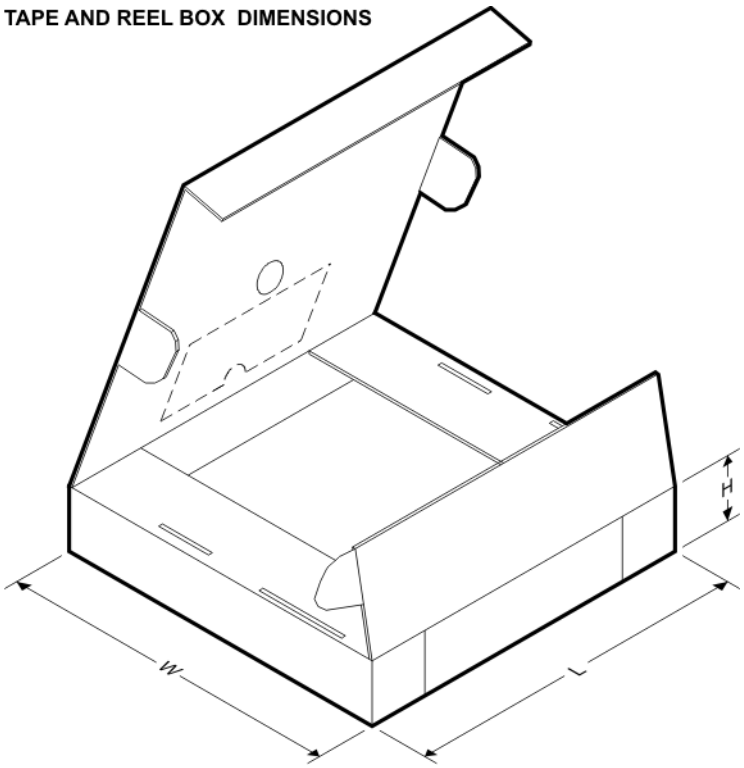
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS251DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



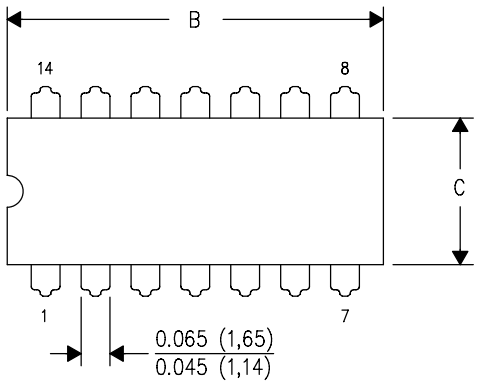
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS251DR	SOIC	D	16	2500	333.2	345.9	28.6

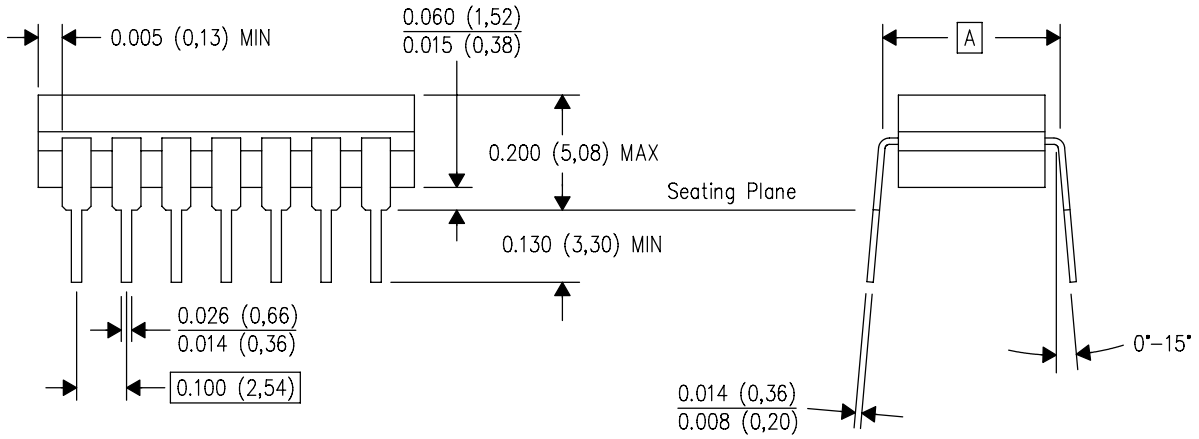
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



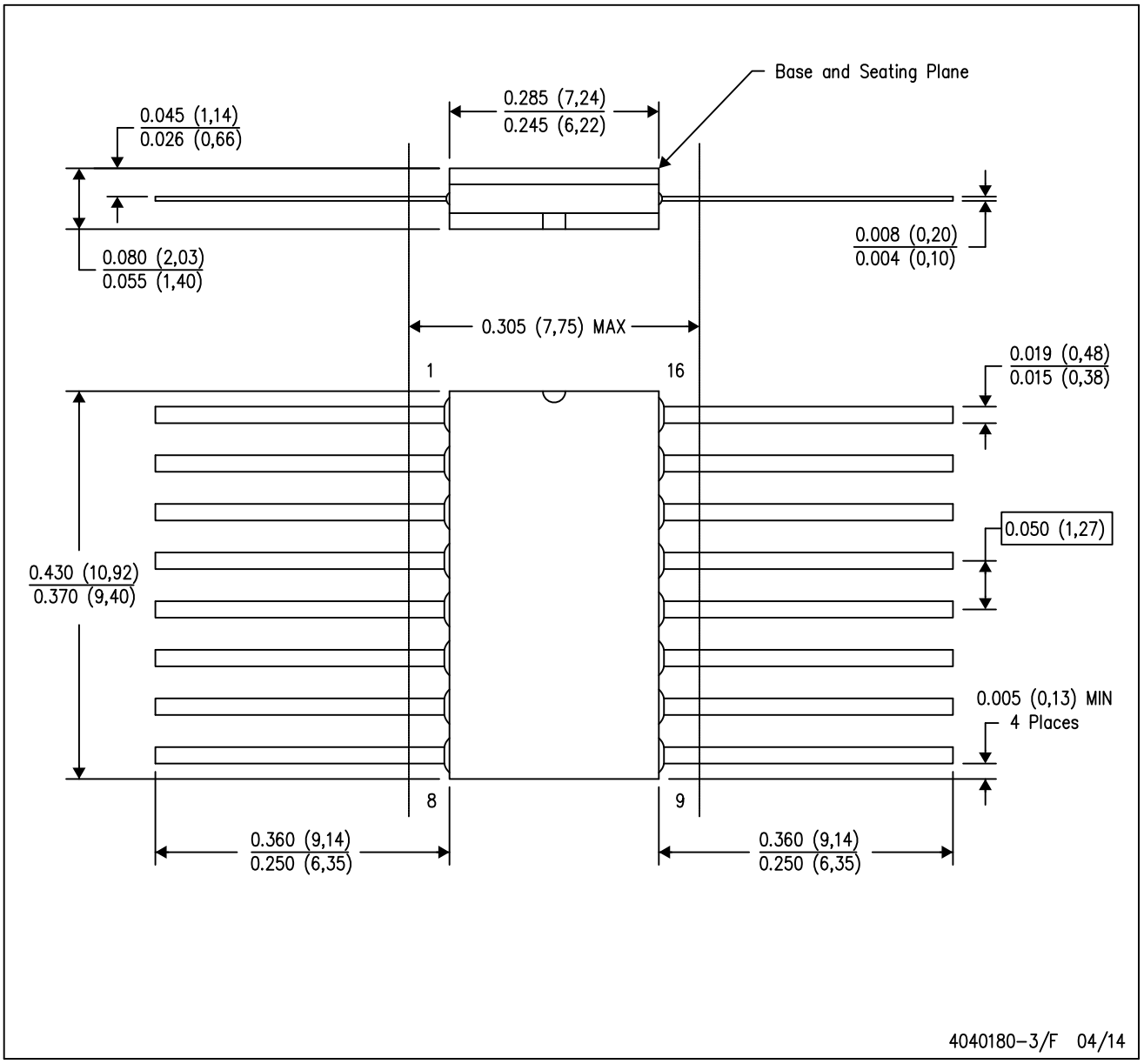
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

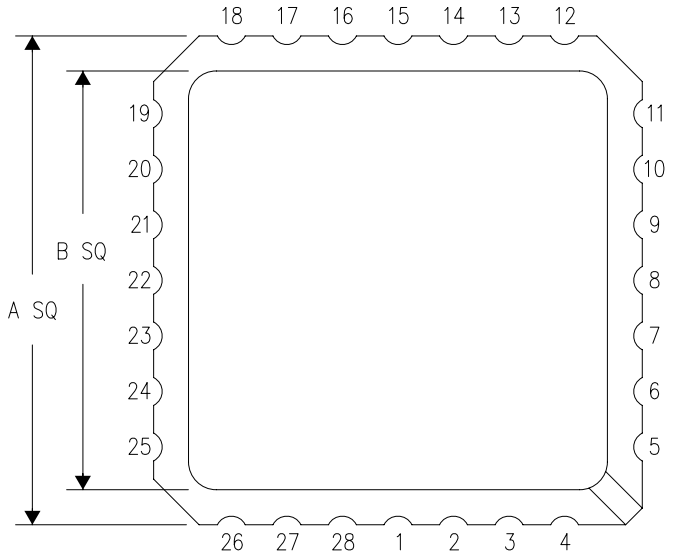
W (R–GDFP–F16) CERAMIC DUAL FLATPACK



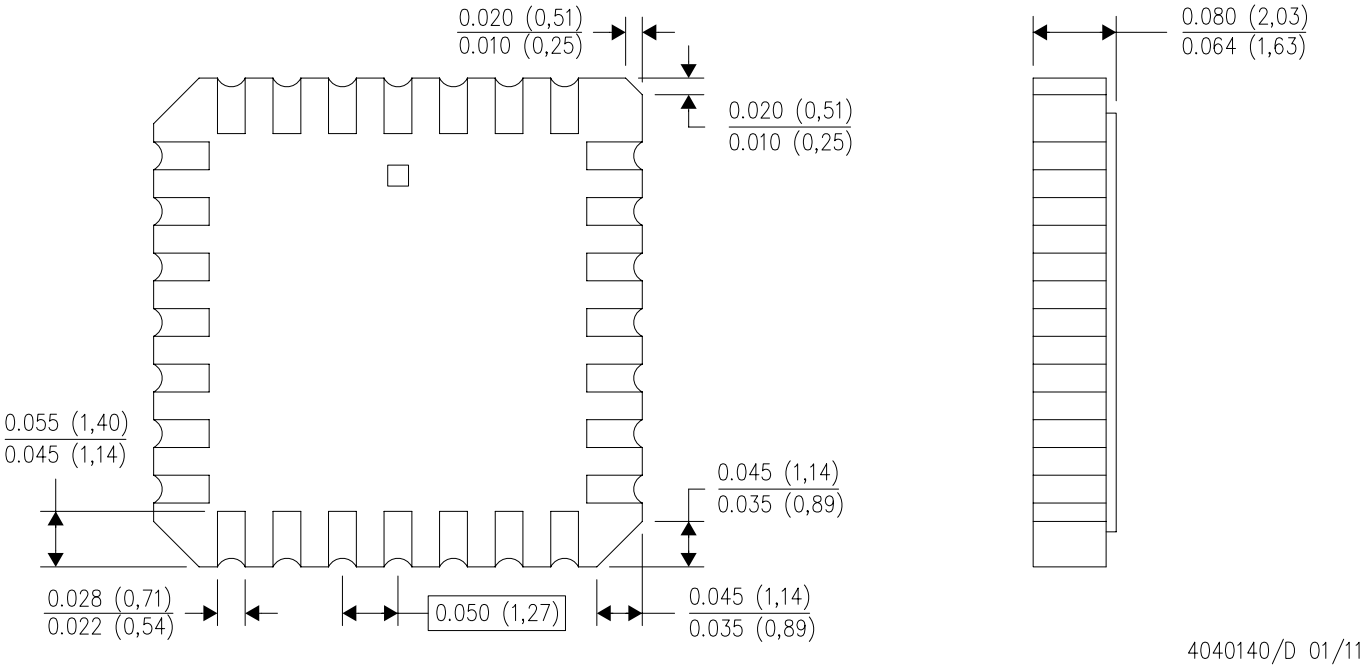
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



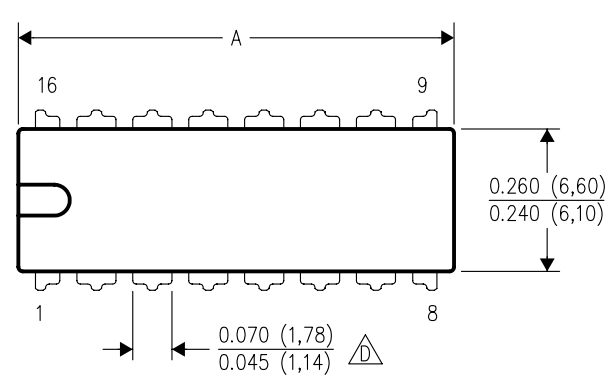
4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

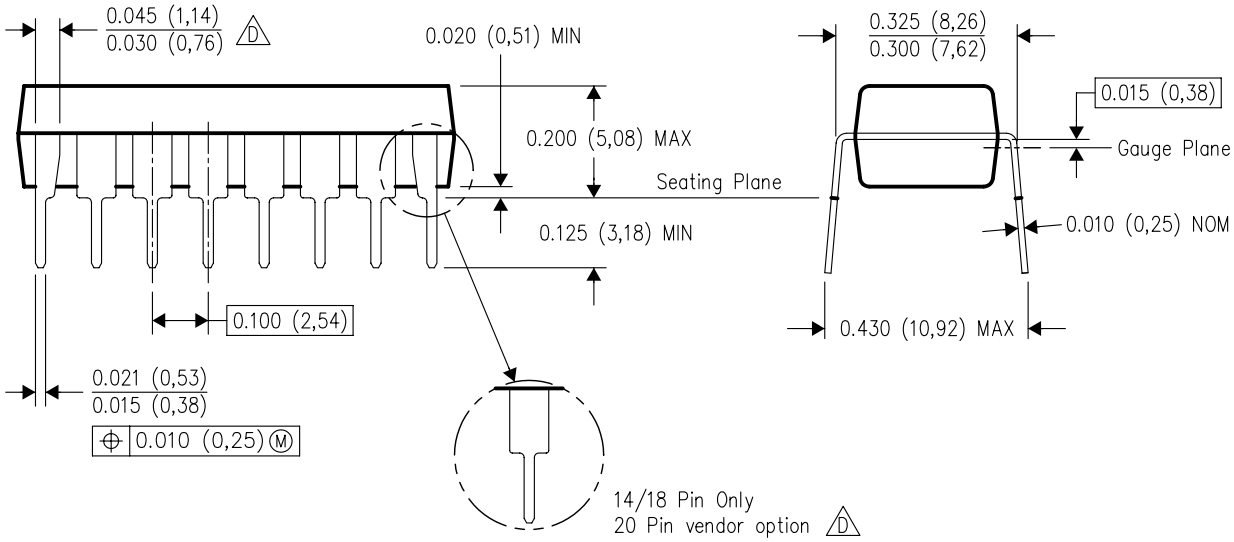
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



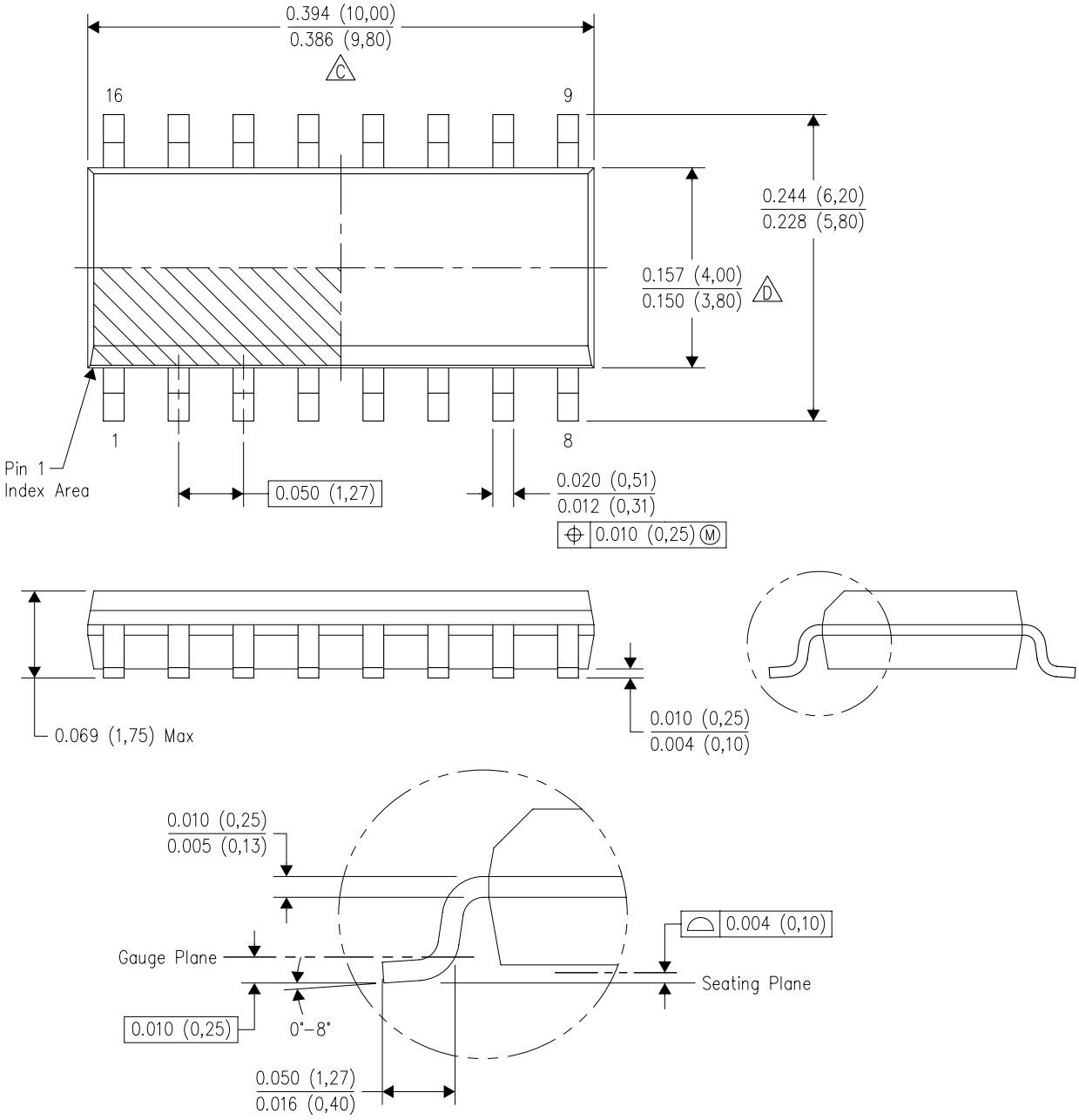
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

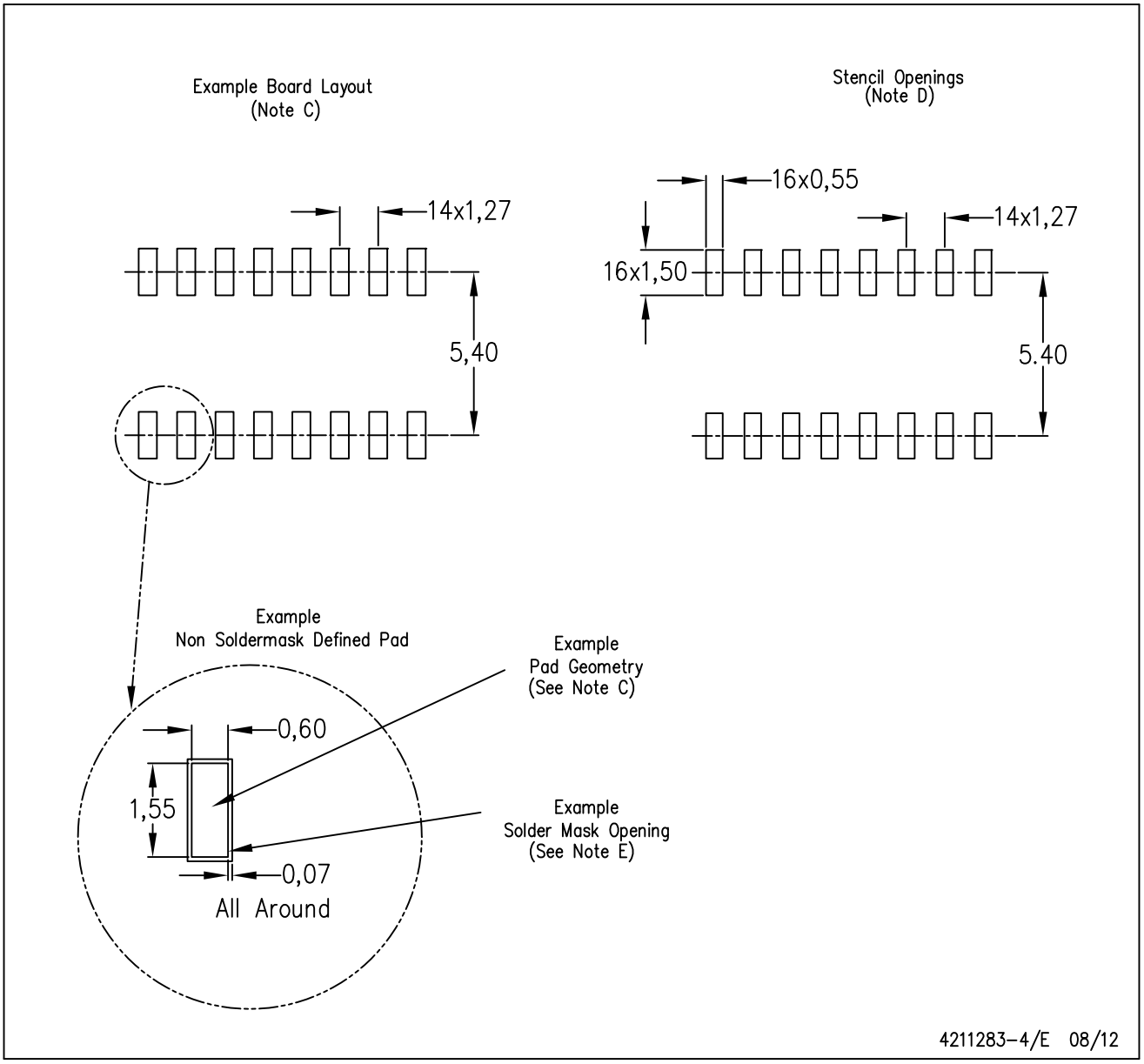
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

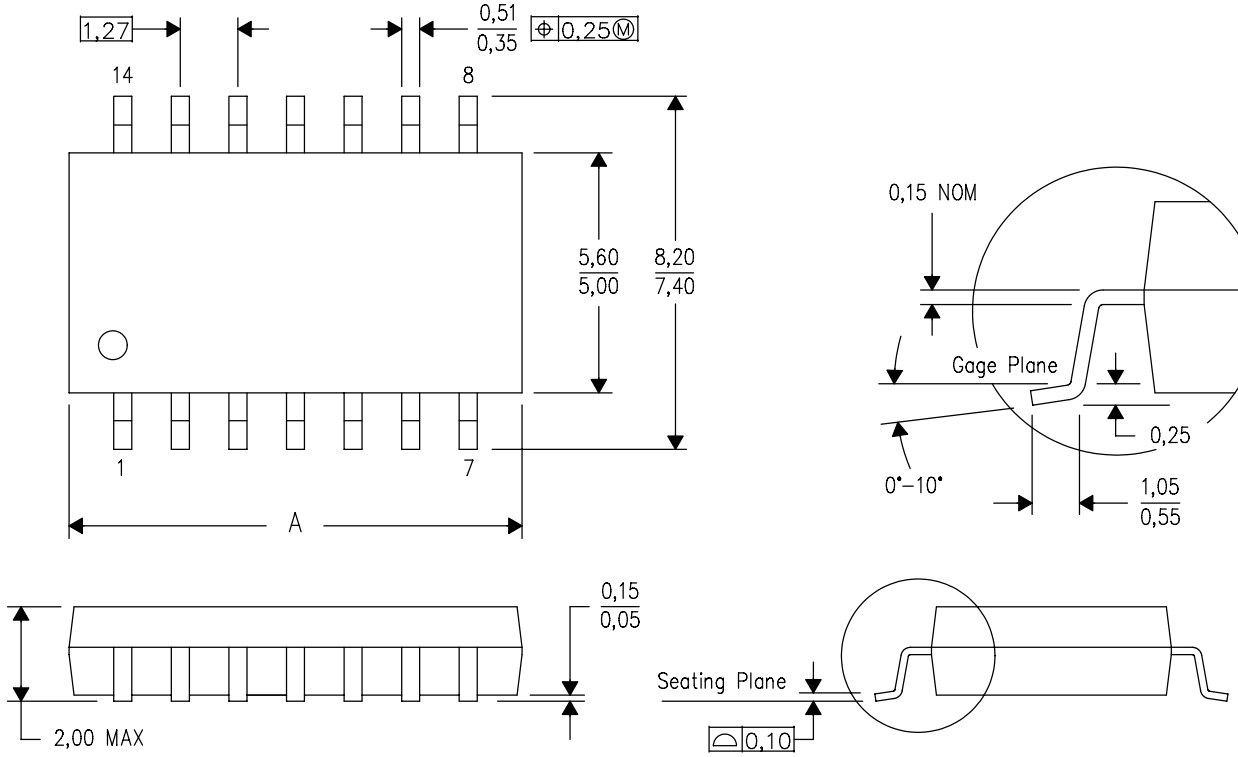


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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